

PATENT

Attv. Dkt. No. AMAT/5931/CMP/ECP/RKK

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Yahalom, et al.

Serial No.: 10/039.275

Confirmation No.: 8306

Filed: January 4, 2002

For: Anode Assembly And
Method Of Reducing
Sludge Formation During
Electroplating

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Group Art Unit: 1775

Examiner: Robert R. Koehler

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

**CERTIFICATE OF FACSIMILE
TRANSMISSION UNDER 37 CFR 1.8**

I hereby certify that this correspondence and the documents referred to as attached therein are being facsimile transmitted to the U.S. Patent and Trademark Office to the fax number indicated by the Examiner, namely, fax number 703-872-9306 to the attention of the named Examiner, on the date below.

Date 7/21/04

Rob Edwards
Signature

Dear Sir:

RESPONSE TO OFFICE ACTION DATED APRIL 2, 2004

In response to the Office Action dated April 2, 2004, having a shortened statutory period for response extended one month to expire on August 2, 2004, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/5931/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper. Remarks/Arguments begin on page 15 of this paper.